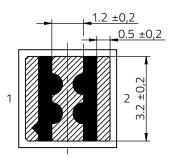
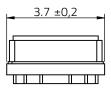
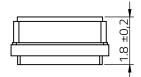
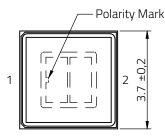
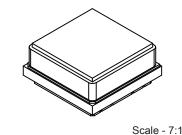
Dimensions: [mm]



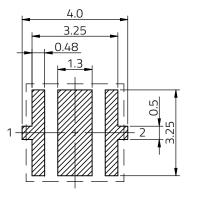








Recommended Land Pattern: [mm]



Scale - 7:1

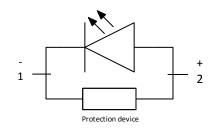
Absolute Maximum Ratings (Ambient Temperature 25°C):

Properties		Value	Unit
Power Dissipation	P _{Diss}	0.75	W
Continuous Forward Current	I _F	100	mA
ESD Threshold/ Human Body Model	V _{ESD HBM}	2000	V
Absolute Thermal Resistance Junction to Solder Point	R _{eJS}	45	K/W
Junction Temperature	T _J	60	°C

Optical Properties:

Chip Technology	AlGaN				
Emitting Color	Ultraviolet-C				
Lens Type	Waterclear				

Schematic:



General Information:

Operating Temperature	-40 °C up to +55 °C
Storage Conditions (in original packaging)	< 40 °C ; < 90 % rH
Storage Conditions (for single parts)	-40 °C up to +100 °C
Moisture Sensitivity Level (MSL)	3

△ WARNING – UV-C

CHECKED

- UV-C LEDs emit UV light that is harmful to eyes and skin.
- Do not look into UV-C LEDs or leave your skin uncovered during operation.
- Wear personal protective equipment to avoid exposure to UV-C light.
- Take appropriate measures to ensure eye and skin safety in your application.
- Attach warning labels on products and systems that use UV-C LEDs.
- Keep out of reach of children.

REVISION

002.000

Avoid any eye and skin exposure to UV-C light!

DATE (YYYY-MM-DD)

2025-02-01



Tel. +49 (0) 79 42 945 - 0 www.we-online.com eiSos@we-online.com

WL-SUMW SMT Ultraviolet Ceramic Waterclear ORDER CODE 15335327CA452 SIZE/TYPE BUSINESS UNIT STATUS PAGE 3535 eiPal Valid 1/10

GENERAL TOLERANCE

DIN ISO 2768-1m

PROJECTION METHOD

YOU EXPECT

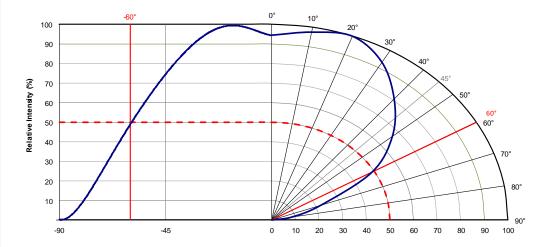
Electrical & Optical Properties:

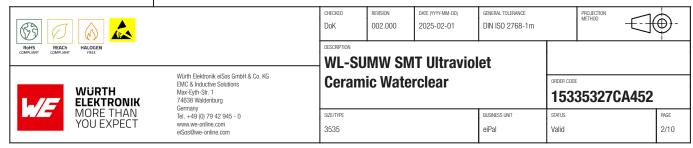
Properties		Test conditions	Value					
rioperues		lest conditions	min.	typ.	max.	Unit		
Peak Wavelength	λ _{Peak}	100 mA		275		nm		
Radiant Flux	Фе	100 mA	13	20		mW		
Forward Voltage	V _F	100 mA		6	7.5	V		
Spectral Bandwidth	Δλ	100 mA		11		nm		
Viewing Angle Phi 0°	2θ _{50%}	100 mA		120		0		

Certification:

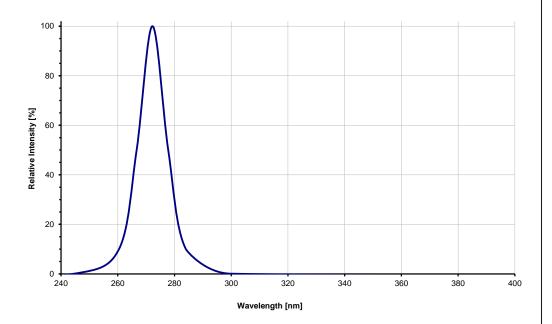
RoHS Approval	Compliant [2011/65/EU&2015/863]
REACh Approval	Conform or declared [(EC)1907/2006]
Halogen Free	Conform [JEDEC JS709B]
Halogen Free	Conform [IEC 61249-2-21]

Viewing Angle:

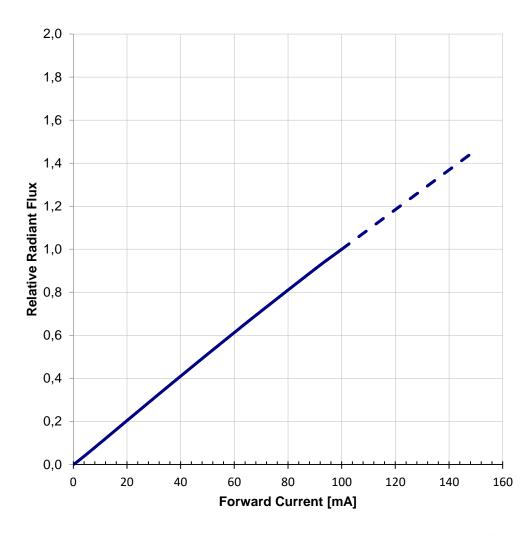




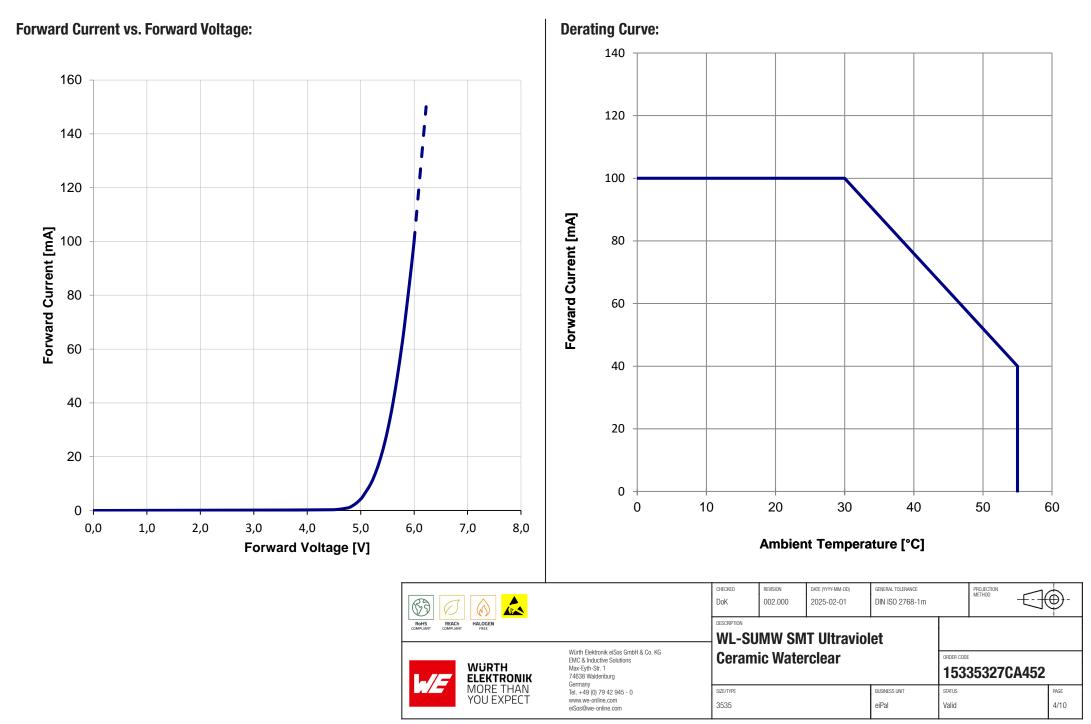
Spectral:



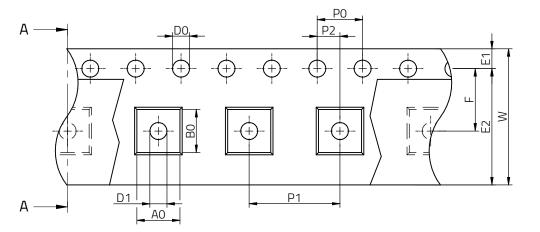
Radiant Flux vs. Forward Current:

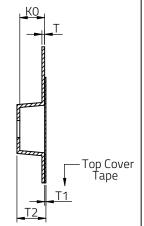


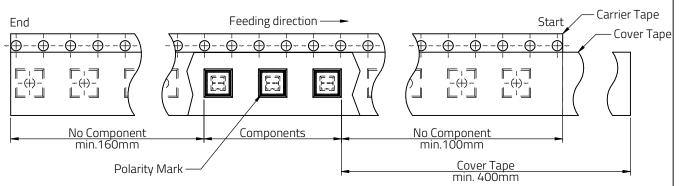




Packaging Specification - Tape: [mm]



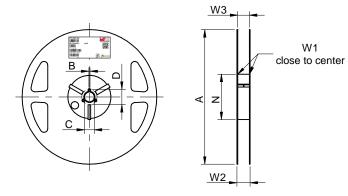


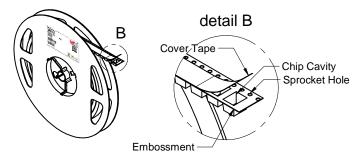


Packaging is referred to the international standard IEC 60286-3:2019

	Таре Туре	A0 (mm)	B0 (mm)	W (mm)	T (mm)	T1 (mm)	T2 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	DO (mm)	D1 (mm)	E1 (mm)	E2 (mm)	F (mm)	Material	Qty. (pcs.)
Tolerance)	typ.	typ.	+0,3/-0,1	ref.	ref.	typ.	typ.	±0,1	±0,1	±0,05	+0,1/-0,0	min.	±0,1	min.	±0,05		
Value	2a	3,80	3,80	12,00	0,25	0,10	2,70	2,50	4,00	8,00	2,00	1,50	1,50	1,75	10,25	5,50	Polystyrene	1000

Packaging Specification - Reel: [mm]





	A (mm)	B (mm)	C (mm)	D (mm)	N (mm)	W1 (mm)	W2 (mm)	W3 (mm)	W3 (mm)	Material
Tolerance	± 2,0	min.	min.	min.	min.	+ 2,0	max.	min.	max.	
Value	178,00	1,50	12,80	20,20	60,00	12,40	18,40	11,90	15,40	Polystyrene



Classification Reflow Profile for SMT components:



Classification Reflow Soldering Profile:

Profile Feature		Value
Preheat Temperature Min	T _{s min}	150 °C
Preheat Temperature Max	T _{s max}	200 °C
Preheat Time t _s from T _{s min} to T _{s max}		max. 60 - 120 seconds
Ramp-up Rate (T _L to T _P)		3 °C/ second max.
Liquidous Temperature	T _L	217 °C
Time t _L maintained above T _L	t _L	max. 60 seconds
Peak package body temperature	T _p	$T_p \le T_c$, see Table below
Time within 5°C of actual peak temperature	t p	max. 10 seconds
Ramp-down Rate (T _P to T _L)		6 °C/ second max.
Time 25°C to peak temperature		max. 220 seconds

refer to IPC/ JEDEC J-STD-020E

Package Classification Reflow Temperature (T_c):

Properties	Volume mm³ <350	Volume mm ³ 350-2000	Volume mm³ >2000				
PB-Free Assembly I Package Thickness < 1.6 mm	260 °C	260 °C	260 °C				
PB-Free Assembly I Package Thickness 1.6 mm - 2.5 mm	260 °C	250 °C	245 °C				
PB-Free Assembly Package Thickness > 2.5 mm	250 °C	245 °C	245 °C				
Applied cycles	2 cycles max.						

refer to IPC/ JEDEC J-STD-020E

			REVISION 002.000	DATE (YYYY-MM-DD) 2025-02-01	GENERAL TOLERANCE DIN ISO 2768-1m		PROJECTION METHOD	-
ROHS REACH HALOGEN COMPLIANT COMPLIANT FREE		DESCRIPTION WL-SU	IMW SN	IT Ultravio				
WURTH ELEKTRONIK MORE THAN YOU EXPECT	Würth Elektronik eiSos GmbH & Co. KG EMC & Inductive Solutions Max-Eyth-Str. 1 74638 Waldenburg Germany	Ceram	ic Wate	rclear		ORDER CODE	35327CA452	2
	Germany Tel. +49 (0) 79 42 945 - 0 www.we-online.com elSos@we-online.com	SIZE/TYPE 3535			BUSINESS UNIT eiPal	status Valid		PAGE 6/10

Further information

Component Libraries:

simulux_RAY

speos_RAY

zemax DAT

zemaxBin_DAT

3D_15335327CA452 Altium Altium_WL-SUMW (23a)

Cadence17-2 Downloads_CADENCE_WL-SUMW (25a) CodeV_RAY CodeV_ray_15335327CA452_5M (1p0)

Eagle Eagle_WL-SUMW (23a) IGS IGS_15335327CA452 **PSpice** PSpice_WL-SUMW (22a) STP STP_15335327CA452

TracePro TXT TracePro txt 15335327CA452 5M (1p0)

asap-and-apex_DIS ASAP-and-APEX_dis_15335327CA452_5M (1p0)

fred DAT Fred_dat_15335327CA452_5M (1p0) fred_TXT Fred_txt_15335327CA452_5M (1p0) LightTools_ray_15335327CA452_5M (1p0) lighttools RAY lighttools_TXT LightTools_txt_15335327CA452_5M (1p0) Lucaray-maker_src_15335327CA452_5M (1p0) lucaray-maker_SRC lucidshape RAY LucidShape_ray_15335327CA452_5M (1p0) lucidshape_TXT LucidShape_txt_15335327CA452_5M (1p0) optalix_DIS OpTaliX_dis_15335327CA452_5M (1p0) optalix TXT OpTaliX_txt_15335327CA452_5M (1p0) opticad DAT OptiCAD_dat_15335327CA452_5M (1p0) opticad_TXT OptiCAD_txt_15335327CA452_5M (1p0) photopia RIR Photopia rir 15335327CA452 5M (1p0)

Simulux_ray_15335327CA452_5M (1p0)

ZemaxBin_dat_15335327CA452_5M (1p0)

Speos_ray_15335327CA452_5M (1p0)

Zemax_dat_15335327CA452_5M (1p0)

Free Sample Order:

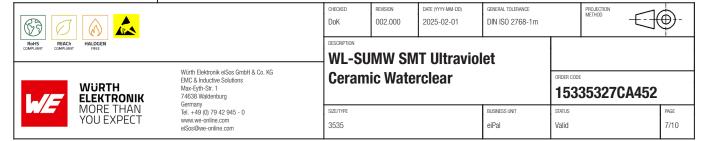
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Tutorials:

LED Application Guide - Learn more about handling, storage and much more (PDF)

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Cautions and Warnings:

The following conditions apply to all goods within the product series of Optoelectronic Components of Würth Elektronik eiSos GmbH & Co. KG:

General:

- This optoelectronic component is designed and manufactured for use in general electronic equipment.
- Würth Elektronik must be asked for written approval (following the PPAP procedure) before incorporating the components into any
 equipment in fields such as military, aerospace, aviation, nuclear control, submarine, transportation (automotive control, train control,
 ship control), transportation signal, disaster prevention, medical, public information network, etc. where higher safety and reliability are
 especially required and/or if there is the possibility of direct damage or human injury.
- Optoelectronic components that will be used in safety-critical or high-reliability applications, should be pre-evaluated by the customer
- The optoelectronic component is designed and manufactured to be used within the datasheet specified values. If the usage and
 operation conditions specified in the datasheet are not met, the wire insulation may be damaged or dissolved.
- Do not drop or impact the components, the component may be damaged
- Würth Elektronik products are qualified according to international standards, which are listed in each product reliability report. Würth
 Elektronik does not warrant any customer qualified product characteristics beyond Würth Elektroniks' specifications, for its validity and
 sustainability over time.
- The responsibility for the applicability of the customer specific products and use in a particular customer design is always within the
 authority of the customer. All technical specifications for standard products also apply to customer specific products.
- Unless Würth Elektroik has given its express consent, the customer is under no circumstances entitled to reverse engineer, disassemble
 or otherwise attempt to extract knowledge or design information from the optoelectronic component

Product specific:

Soldering

- The solder profile must comply with the technical product specifications. All other profiles will void the warranty.
- All other soldering methods are at the customers' own risk.
- The soldering pad pattern shown above is a general recommendation for the easy assembly of optoelectronic component. If a high
 degree of precision is required for the selected application (i.e. high density assembly), the customer must ensure that the soldering pad
 pattern is optimized accordingly.

Cleaning and Washing:

Washing agents used during the production to clean the customer application might damage or change the characteristics of the
optoelectronic component body, marking or plating. Washing agents may have a negative effect on the long-term functionality of the
product.

Using a brush during the cleaning process may break the optoelectronic component body. Therefore, we do not recommend using a
brush during the PCB cleaning process.

Potting:

If the product is potted in the customer application, the potting material might shrink or expand during and after hardening. Shrinking
could lead to an incomplete seal, allowing contaminants into the optoelectronic component body, pins or termination. Expansion could
damage the components. We recommend a manual inspection after potting to avoid these effects.

Storage Conditions:

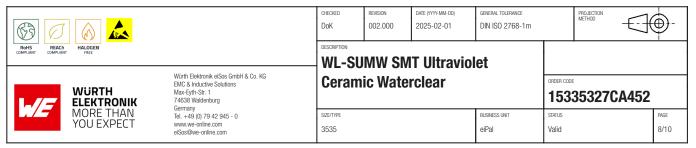
- A storage of Würth Elektronik products for longer than 12 months is not recommended. Within other effects, the terminals may suffer
 degradation, resulting in bad solderability. Therefore, all products shall be used within the period of 12 months based on the day of
 shipment.
- Do not expose the optoelectronic component to direct sunlight.
- The storage conditions in the original packaging are defined according to DIN EN 61760-2.
- For a moisture sensitive component, the storage condition in the original packaging is defined according to IPC/JEDEC-J-STD-033. It is
 also recommended to return the optoelectronic component to the original moisture proof bag and reseal the moisture proof bag again.
- The storage conditions stated in the original packaging apply to the storage time and not to the transportation time of the components.

Packaging:

The packaging specifications apply only to purchase orders comprising whole packaging units. If the ordered quantity exceeds or is
lower than the specified packaging unit, packaging in accordance with the packaging specifications cannot be ensured.

Handling:

- · Violation of the technical product specifications such as exceeding the nominal rated current, will void the warranty.
- The product design may influence the automatic optical inspection.
- Certain optoelectronic component surfaces consist of soft material. Pressure on the top surface has to be handled carefully to prevent negative influence to the function and reliability of the optoelectronic components.
- ESD prevention methods need to be applied for manual handling and processing by machinery.
- Resistors for protection are obligatory.
- Luminaires in operation may harm human vision or skin on a photo-biological level. Therefore direct light impact shall be avoided.
- In addition to optoelectronic components testing, products incorporating these devices have to comply with the safety precautions given
 in IEC 60825-1, IEC 62471 and IEC 62778
- Please be aware that Products provided in bulk packaging may get bent and might lead to derivations from the mechanical
 manufacturing tolerances mentioned in our datasheet, which is not considered to be a material defect. Please be aware that Products
 provided in bulk packaging may get bent and might lead to derivations from the mechanical manufacturing tolerances mentioned in our
 datasheet, which is not considered to be a material defect.



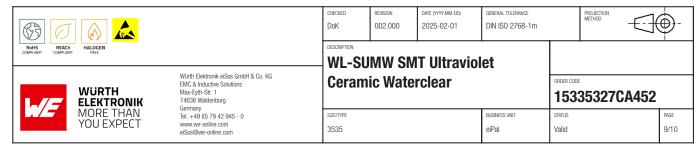
Technical specification:

- The typical and/or calculated values and graphics of technical parameters can only reflect statistical figures. The actual parameters of
 each single product, may differ from the typical and/or calculated values or the typical characteristic line.
- On each reel, only one bin is sorted and taped. The bin is defined on intensity, chromaticity coordinate or wavelength and forward voltage.
- In order to ensure highest availability, the reel binning of standard deliveries can vary. A single bin cannot be ordered. Please contact us
 in advance, if you need a particular bin sorting before placing your order.
- Test conditions are measured at the typical current with pulse duration < 30ms.
- Optical properties are measured according the CIE 127:2007 standard.
- Wavelength tolerance under measurement conditions ± 2nm.
- Optical intensity tolerance under measurement conditions ±15%.
- Forward voltage tolerance under measurement conditions ± 0.1V.
- CCT tolerance of x and y coordinate of \pm 0.01 and CRI tolerance of \pm 2 is allowed.

In the characteristics curves, all values given in dotted lines may show a higher deviation than the parameters mentioned above.

These cautions and warnings comply with the state of the scientific and technical knowledge and are believed to be accurate and reliable. However, no responsibility is assumed for inaccuracies or incompleteness.

The customer has the sole responsibility to ensure that he uses the latest version of this datasheet, which is available on Würth Elektronik's homepage. Unless otherwise agreed in writing (i.e. customer specific specification), changes to the content of this datasheet may occur without notice, provided that the changes do not have a significant effect on the usability of the optoelectronic components



Important Notes

The following conditions apply to all goods within the product range of Würth Elektronik eiSos GmbH & Co. KG:

1. General Customer Responsibility

Some goods within the product range of Würth Elektronik eiSos GmbH & Co. KG contain statements regarding general suitability for certain application areas. These statements about suitability are based on our knowledge and experience of typical requirements concerning the areas, serve as general guidance and cannot be estimated as binding statements about the suitability for a customer application. The responsibility for the applicability and use in a particular customer design is always solely within the authority of the customer. Due to this fact it is up to the customer to evaluate, where appropriate to investigate and decide whether the device with the specific product characteristics described in the product specification is valid and suitable for the respective customer application or not.

2. Customer Responsibility related to Specific, in particular Safety-Relevant Applications

It has to be clearly pointed out that the possibility of a malfunction of electronic components or failure before the end of the usual lifetime cannot be completely eliminated in the current state of the art, even if the products are operated within the range of the specifications. In certain customer applications requiring a very high level of safety and especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health it must be ensured by most advanced technological aid of suitable design of the customer application that no injury or damage is caused to third parties in the event of malfunction or failure of an electronic component. Therefore, customer is cautioned to verify that data sheets are current before placing orders. The current data sheets can be downloaded at www.we-online.com.

3. Best Care and Attention

Any product-specific notes, cautions and warnings must be strictly observed. Any disregard will result in the loss of warranty.

4. Customer Support for Product Specifications

Some products within the product range may contain substances which are subject to restrictions in certain jurisdictions in order to serve specific technical requirements. Necessary information is available on request. In this case the field sales engineer or the internal sales person in charge should be contacted who will be happy to support in this matter.

5. Product R&D

Due to constant product improvement product specifications may change from time to time. As a standard reporting procedure of the Product Change Notification (PCN) according to the JEDEC-Standard inform about minor and major changes. In case of further queries regarding the PCN, the field sales engineer or the internal sales person in charge should be contacted. The basic responsibility of the customer as per Section 1 and 2 remains unaffected.

6. Product Life Cycle

Due to technical progress and economical evaluation we also reserve the right to discontinue production and delivery of products. As a standard reporting procedure of the Product Termination Notification (PTN) according to the JEDEC-Standard we will inform at an early stage about inevitable product discontinuance. According to this we cannot guarantee that all products within our product range will always be available. Therefore it needs to be verified with the field sales engineer or the internal sales person in charge about the current product availability expectancy before or when the product for application design-in disposal is considered. The approach named above does not apply in the case of individual agreements deviating from the foregoing for customer-specific products.

7. Property Rights

All the rights for contractual products produced by Würth Elektronik eiSos GmbH & Co. KG on the basis of ideas, development contracts as well as models or templates that are subject to copyright, patent or commercial protection supplied to the customer will remain with Würth Elektronik eiSos GmbH & Co. KG does not warrant or represent that any license, either expressed or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, application, or process in which Würth Elektronik eiSos GmbH & Co. KG components or services are used.

8. General Terms and Conditions

Unless otherwise agreed in individual contracts, all orders are subject to the current version of the "General Terms and Conditions of Würth Elektronik eiSos Group", last version available at www.we-online.com.

